

CUSTOMER: _____

DATE: _____

APPROVAL SPECIFICATION

PRODUCT NAME: SMD high current power inductor

YOUR PART NO. :

OUR PART NO. : MGHC0906R1-R12K-LF

VERSION: V1.1

RECEPTION

THE SPECIFICATION HAS BEEN ACCEPTED.

DATE:

COMPANY:

CFMD

CHKD

RCVD

MANUFACTURING NAME

深圳市麦捷微电子科技股份有限公司

SHENZHEN MICROGATE TECHNOLOGY CO., LTD

Address: Microgate Technology Building, No.6, 2nd Ln,
Longtian Science Park, 6075 pingshan Road, Shenzhen.

Postcode :518110

TEL: 86-755-28085000

FAX: 86-755-28085605

CFMD.	CHKD.	DSGD.
Dylan	王玉生	盛 涛

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Component SPEC Version Record

Rev.	Effective Date	Changed Contents	Change Reasons	Approved By
1.0	Sept.3.2019	New released	/	Dylan
1.1	May.20.2021	Change dimensions and package quantities	/	Dylan

1. Scope

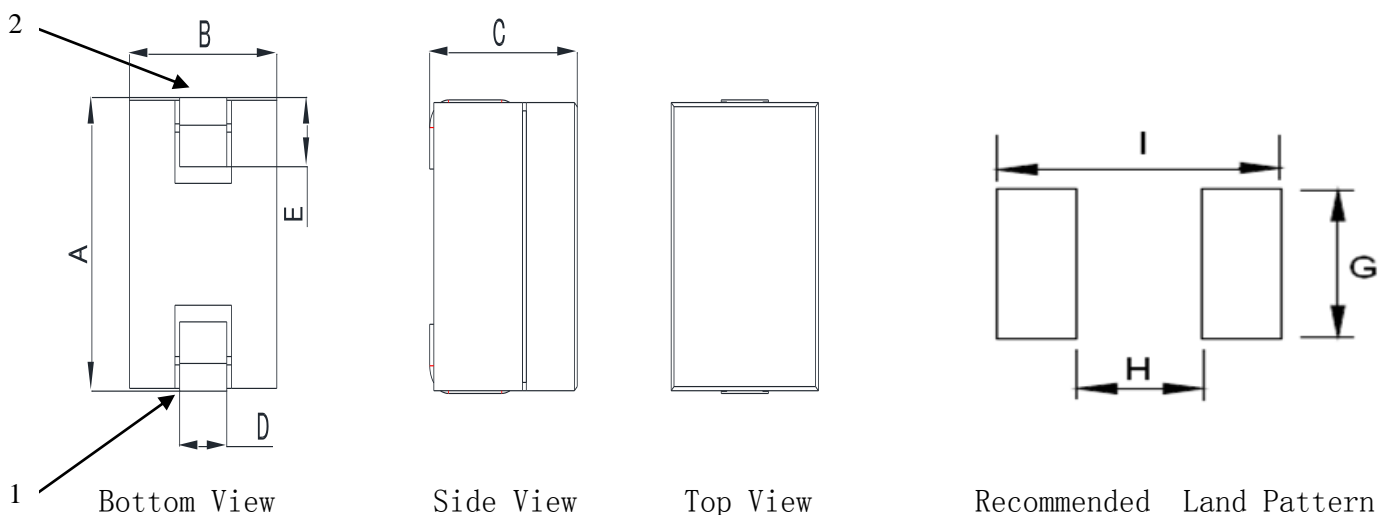
This specification applies to the MGHC0906R1 series of SMD power inductor.

2. Product Identification

MGHC 0906 R1 - R12 K - LF
① ② ③ ④ ⑤ ⑥

- ① Product Symbol (High current SMD power inductor)
- ② Product dimensions
- ③ Core Material
- ④ Inductance Value: (R12:120nH;)
- ⑤ Inductance Tolerance: (K: $\pm 10\%$; M: $\pm 20\%$;)
- ⑥ Lead free product.

3. Appearance and Dimensions



Dimensions in mm							
A	B	C	D	E	G	H	I
10.0 max	6.40 max	8.00 max	2.14 ± 0.20	2.30 ± 0.20	2.54 Typ	4.00Typ	10.4 Typ

Tolerance are $\pm 0.25\text{mm}$ unless otherwise specified.

Soldering surfaces to be coplanar within 0.10mm.

PCB tolerance $\pm 0.10\text{mm}$ unless otherwise specified

4. Testing Conditions

Unless otherwise specified

Temperature : Ordinary Temperature (5 to 35℃)

Humidity : Ordinary Humidity (25 to 85% RH)

Atmospheric Pressure : 86 to 106 kPa

In case of doubt

Temperature : 20±2℃

Humidity : 60 to 75% RH

Atmospheric Pressure : 86 to 106 kPa

5. Electrical Characteristics

Microgate Part No.	Customer Part No.	Inductance (nH)	DCR ^{•1} (mΩ)	Isat ^{•2} @25℃ (A)	Isat ^{•3} @100℃ (A)	Irms ^{•4} (A)
MGHC0906R1-R12K-LF	-	120±10%	0.29±5%	81	70	51

* L test condition: 100KHz & 1.0V at 25℃ ambient;

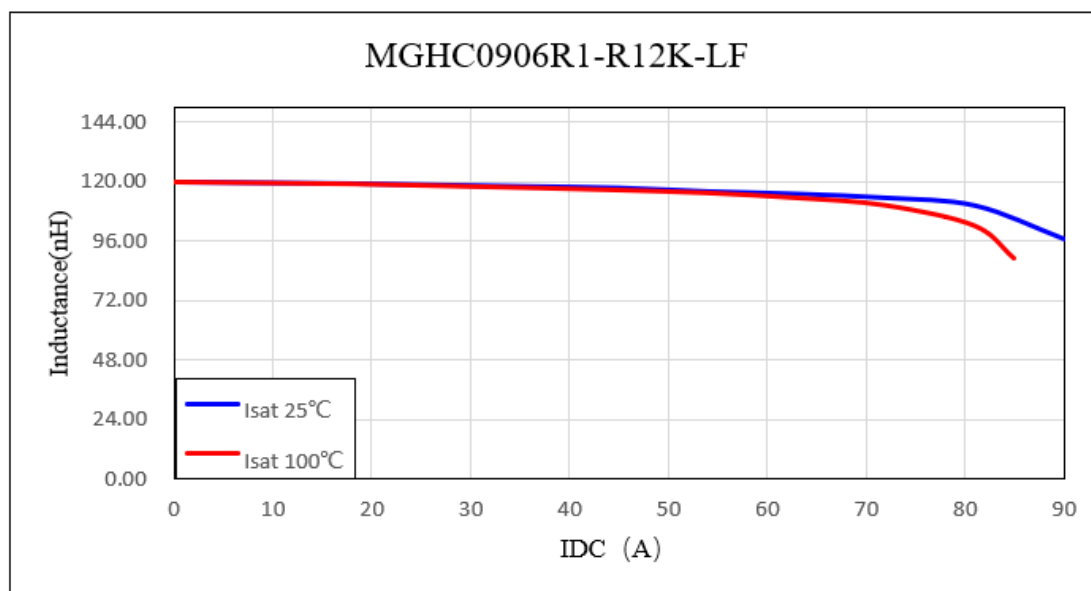
* ^{•1}: DCR: The nominal DCR is measured from point "1" to point "2" as 3.

^{•2}: Isat@25℃: direct current at which the inductance drops approximate 20% from its value without current at 25℃;

^{•3}: Isat@100℃: direct current at which the inductance drops approximate 20% from its value without current at 100℃;

^{•4}: Irms: direct current when the temperature of the product rise (ΔT=40℃) from 20℃ ambient.

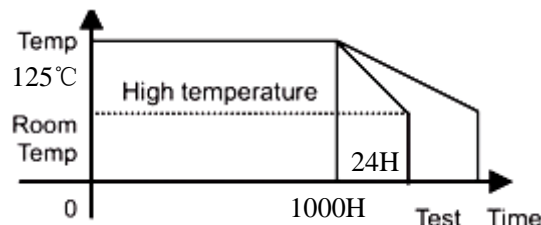
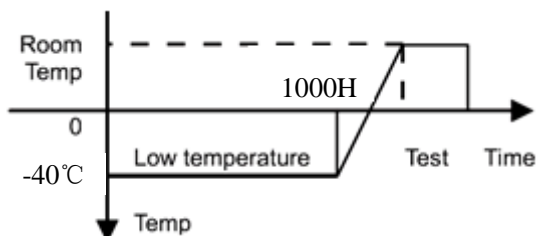
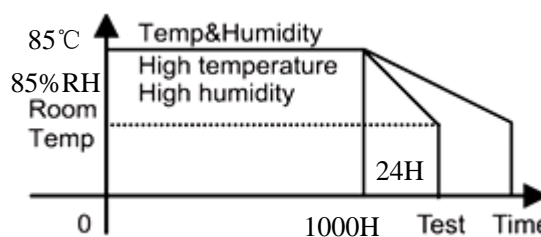
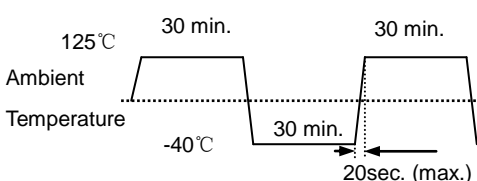
Inductance Characteristics

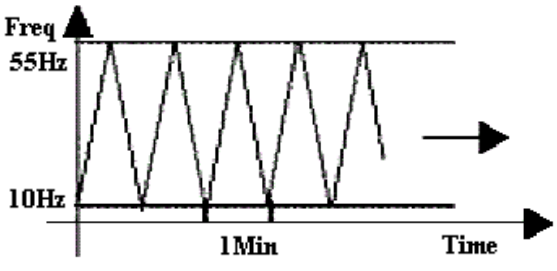
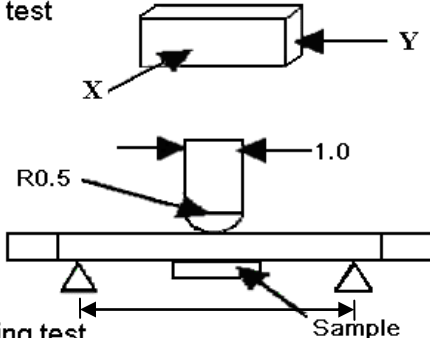
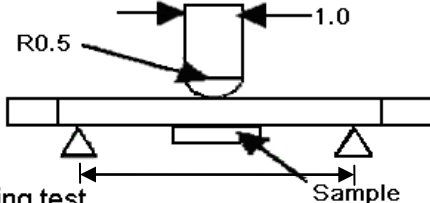


6. Condition of work

Operating temperature range: -40℃ ~ +125℃.(Including self-heating)

7. Reliability and Test Condition

Item	Required Characteristics	Test Method/Condition
High temperature resistance		<p>Temperature: $125 \pm 2^\circ\text{C}$ Time : 1000 hours Measurement at 24 ± 4 hours after test conclusion.</p> 
Low temperature resistance	<ol style="list-style-type: none"> No case deformation or change in appearance. $\Delta L /L \leq 10\%$ 	<p>Temperature : $-40 \pm 2^\circ\text{C}$ Time : 1000 hours Measurement at 24 ± 4 hours after test conclusion.</p> 
Humidity test		<ol style="list-style-type: none"> Exposure : Temperature: 85°C, Humidity :85% RH Time : 1000 hours. Tested while the specimens are still in the chamber. Measurement at 24 ± 4 hours after test conclusion. 
Thermal shock test	<ol style="list-style-type: none"> No case deformation or change in appearance. $\Delta L /L \leq 10\%$ 	<p>First -40°C for T time, last 125°C T time as 1 cycle. Go through 1000 cycles.</p> 

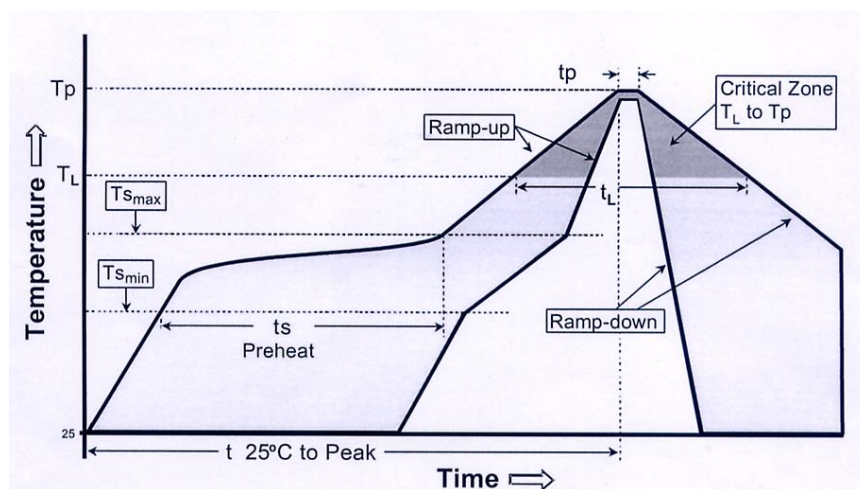
Item	Required Characteristics	Test Method/Condition
Solderability test	Terminal area must have 95% min. solder coverage.	Dip pads in flux then dip in solder pot at $245 \pm 5^{\circ}\text{C}$ for 5 ± 0.1 second. Solder: :Sn96.5%、Ag3%、Cu0.5% Flux: rosin flux.
Heat endurance of reflow soldering	1. No case deformation or change in appearance. 2. $ \Delta L/L \leq 10\%$	Refer to the next page reflow curve Go through 3 times. The peak temperature: $260 \pm 5^{\circ}\text{C}$
Vibration test		Apply frequency 10~55Hz. 1.5mm amplitude in each of perpendicular direction for 2 hours in each 3 mutually perpendicular directions.(total 6 hours) 
Drop test		Packaged & drop down from 1m with $981\text{m/s}^2(100\text{G})$ attitude in 1 angle 1 ridges & 2surfaces orientations.
Terminal strength push test	Pulling test: Define: Solder the products on testing PCB using eutectic solder. Then apply a force in the direction of the arrow. 17.64N force. Keep time $\geq 10\text{s}$ Bending test: Soldering the products on PCB, after the pulling test and bending test, terminal should not pull off.	Bend the testing PCB at middle point, the deflection shall be 2mm. Pressurizing Speed: 0.5mm/sec, Keep time: $60 \pm 1\text{s}$, Pulling test  Bending test 
Loading Under Humidity Heat	1. No case deformation or change in appearance. 2. $ \Delta L/L \leq 10\%$	1. Exposure : Temperature: $60 \pm 2^{\circ}\text{C}$, Humidity : $93 \pm 3\%$ RH Time : 1000 hours. Apply rated current 2. Tested while the specimens are still in the chamber. 3. Measurement at 24 ± 4 hours after test conclusion.
Loading at High Temperature	1. No case deformation or change in appearance. 2. $ \Delta L/L \leq 10\%$	1. Temperature: $85 \pm 2^{\circ}\text{C}$ 2. Time : 1000 hours 3. Apply rated current 4. Measurement at 24 ± 4 hours after test conclusion

8. Recommended Soldering Conditions

Product can be applied to reflow soldering.

(1) Reflow soldering conditions

Reflow curve



Profile Feature		Lead-Free Assembly
Average Ramp-Up Rate (Ts max. to Tp)		3°C/second max.
Preheat	– Temperature Min (Ts min.)	150 °C
	– Temperature Max (Ts max.)	200 °C
	– Time (ts min to ts max.)	60-180 seconds
Time maintained above	– Temperature (TL)	217 °C
	– Time (tL)	60-150 seconds
Peak/Classification Temperature (Tp)		260 °C
Peak/Classification Time (Tp)		3-4 seconds
Time within 5 °C of actual Peak Temperature (Tp)		20-40 seconds
Ramp-Down Rate		6 °C/second max.
Time 25 °C to Peak Temperature		8 minutes max.

Note 1: All temperatures refer to topside of the package, measured on the package body surface.

(2) The method on Re-work with using the iron:

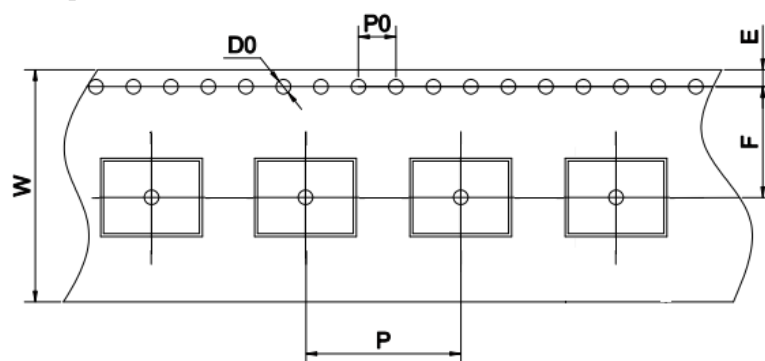
The following conditions must be strictly followed when using a soldering iron

Pre-heating	150°C, 1 minute
Tip temperature	350°C max
Soldering iron output	80w max
End of soldering iron	φ1mm max
Soldering time	3 seconds max

Product once removes from the circuit board may not be used again.

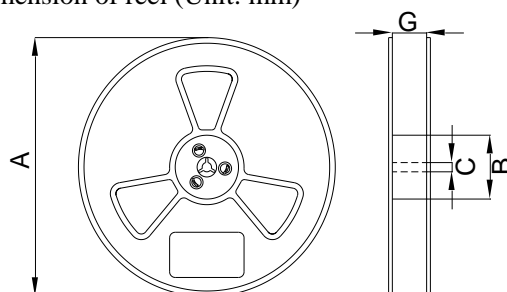
9. Package Information

9.1 Dimension of tape (Unit: mm)



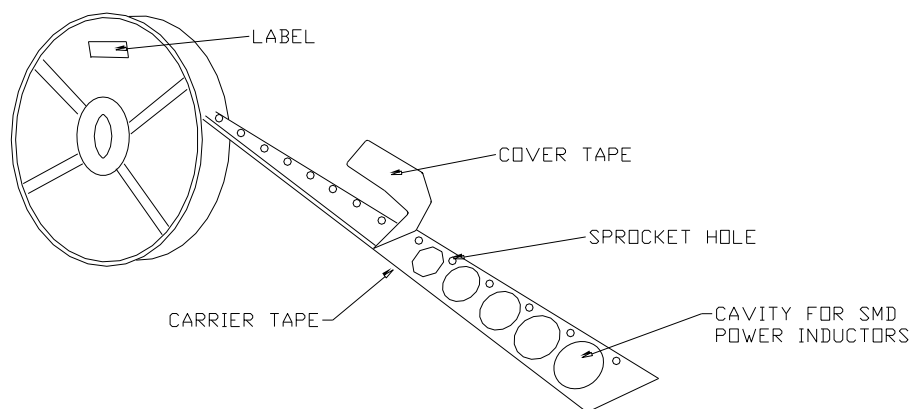
W	E	F	P	P0	D0
24.0±0.30	1.75±0.10	11.5±0.10	12.0±0.10	4.00±0.10	1.50±0.10

9.2 Dimension of reel (Unit: mm)



Symbol	Dimension
A	330
B	100
C	20.4
G	24.5

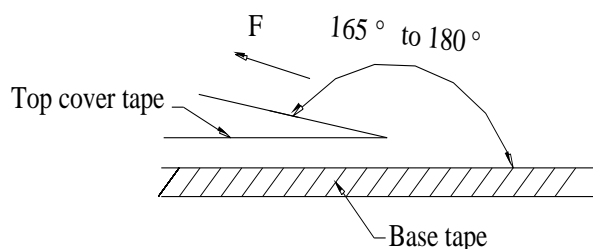
9.3 Taping figure and drawing direction



9.4 Packaging quantities: 700PCS/Reel.

9.5 Peeling strength of cover tape:

The peel force of top cover tape shall be between 0.1N to 1.3N



Room Temp. (°C)	Room Humidity (%)	Room aim (hpa)	Peel Speed Mm/min
5-35	45-85	860-1060	300

10. Products Storage

(1) Storage period

Products which inspected in MICROGATE over 12 months ago should be examined and used, which can be confirmed with inspection No. marked on the container. Solderability should be checked if this period is exceeded.

(2) Storage conditions

Products should be storage in the warehouse on the following conditions:

Temperature: -10 ~+ 40°C

Humidity : Less than 80% relative and humidity

No rapid change on temperature and humidity

- (3) Don't keep products in corrosive gases such as sulfur, chlorine gas or acid, or it may cause oxidization of electrode, resulting in poor solderability.
- (4) Products should be storage on the palette for the prevention of the influence from humidity, dust and so on.
- (5) Products should be storage in the warehouse without heat shock, vibration, direct sunlight and so on.
- (6) Products should be storage under the airtight packaged condition.